Express Mail No.: EV529787097US

International Application No.: PCT/JP2004/017397 International Filing Date: November 11, 2004

Preliminary Amendment

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- 1. (Original) A conductive paste containing an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α -terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d-dihydrocarvyl acetate as a solvent.
- 2. (Original) A conductive paste in accordance with Claim 1, wherein the weight-average molecular weight of the acrylic system resin is equal to or larger than 450,000 and equal to or smaller than 900,000.
- 3. (Currently Amended) A conductive paste in accordance with Claim 1-or-2, wherein the acid value of the acrylic system resin is equal to or larger than 5 mgKOH/g and equal to or smaller than 25 mgKOH/g.
- 4. (Original) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component comprising a step of printing a conductive paste containing an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α-terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perylil acetate, I-carvyl acetate, and d- dihydrocarvyl acetate as a solvent on a ceramic green sheet containing a butyral system resin as a binder in a predetermined pattern to form an electrode layer.

Express Mail No.: EV529787097US

International Application No.: PCT/JP2004/017397

International Filing Date: November 24, 2004

Preliminary Amendment

5. (Original) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, which further comprises a step of printing a dielectric paste containing an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α-terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d-dihydrocarvyl acetate as a solvent on the ceramic green sheet in a complementary pattern to that of the electrode layer after drying the electrode layer, thereby forming a spacer layer.

- 6. (Original) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with Claim 4, which further comprises a step of printing a dielectric paste containing an acrylic system resin as a binder and at least one solvent selected from a group consisting of limonene, α-terpinyl acetate, I-dihydrocarvyl acetate, I-menthone, I-perillyl acetate, I-carvyl acetate, and d-dihydrocarvyl acetate as a solvent on the ceramic green sheet in a complementary pattern to that of the electrode layer prior to forming the electrode layer, thereby forming a spacer layer.
- 7. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with any-one-of Claims 4-to-6, wherein the weight-average molecular weight of the acrylic system resin is equal to or larger than 450,000 and equal to or smaller than 900,000.
- 8. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with any one of Claims 4-to 7, wherein the acid value of the acrylic system resin is equal to or larger than 5 mgKOH/g and equal to or smaller than 25 mgKOH/g.

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9. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with any one of Claims 4 to 8, wherein the degree of polymerization of the butyral system resin is equal to or larger than 1,000.

10. (Currently Amended) A method for manufacturing a multi-layered unit for a multi-layered ceramic electronic component in accordance with any one of Claims 4-to 9, wherein the butyral degree of the butyral system resin is equal to or larger than 64 mol % and equal to or smaller than 78 mol %.